ITEM OPPORTUNITY SYNOPSIS

Scouting Number:	2024-026
Name of the item to be scouted:	Identification Badge
State item to be used in:	Georgia
Describe the Item:	
Please describe the item application/the end use of the item.	Need manufacturer with plastics OVER MOLD or COLD PRESS capabilities, and final product assembly. Product: Id Badge with Bio metric identification and activation - The Digital Me Smart Card holds BLE, NFC and RFId with wireless charging. The fingerprint sensor registers/authenticates to one user and only this user can use the badge to be granted access to a building, data center, medicine cabinet - any type of reader that permits access control. – plastics OVER MOLD or COLD PRESS + limited assembly
Supplier Information:	
Type of Supplier Being Sought (select from the list below):	
Manufacturer	x
Contract Manufacturer	
Distributor	
Other (Please Specify)	
Reason for Scouting Submission (select from the list below)	
2nd Supplier	
Price	
Re-Shore	
Past supplier no longer available	
New Product Startup	x
BABA	
Other (Please Specify)	
Summary of Technical Specifications and Performance Requirements:	
Describe the manufacturing processes (elaborate to provide as much detail as possible)	Enclosure is the key manufacturing process needed. This encloses the device and makes it more robust and water resistant. Need a manufacturer to complete (final) parts assembly and then "enclose" the Id badge using OVER MOLD or COLD PRESS technique. Assembly parts: We have the fingerprint sensors, the pre-assembled pcb boards/components and radio coils. Need a manufacturer to assemble with an over mold or cold press technique.
Provide dimensions / size / tolerances / performance specifications of the item	4"x3.5"x0.10" - dimensions can differ due to outer modeling. (See attached drawings for more details.)
List required materials needed to make the product, including materials of product components, if applicable	We will provide the PCB boards, coils, and fingerprint sensors. Component list: Hip Science, LLC. 3218 E. Colonial Dr. Suite G. Orlando, FL. 32803 Source Data From: SchalgeCardREVB.PrjPcb Project: SchalgeCardREVB.PrjPcb Variant: None See attached materials list.
Are there applicable certification requirements?	
Yes	
No	x
Please explain:	
Are there any applicable regulations that apply to the production of this item?	
Yes	
No	x
Please explain:	
Are there any other standards / requirements?	
Yes	
No	x
Please explain:	
Additional Comments:	
Additional technical comments:	

Volume and Pricing:	
Estimated Potential Business Volume (i.e. #units per day, month, year):	Our first lot will be 5-10k then once proven in 100k - every quarter
Estimated Target Price/Unit Cost Information:	Bill of materials (BOM) cost is approximately 10 dollars and want to keep the overall unit cost down to 15 dollars a unit
Delivery Requirements:	
When is it needed by? (Immediate, 30 days, 6 months, etc.)	3 months
Describe packaging requirements (i.e. individually/group packaging, etc.)	packaging can be in groups of 100 with protection on the fingerprint sensor.
Where will this item be shipped?	Atlanta Ga - 120 Technology Parkway, Peachtree Corners, Ga 300092
Additional Comments:	
Is there other information you would like to include?	

DWG NO.	SHT
MODIREVA	1

REVISIONS

REV	DESCRIPTION	ECR	DATE	APPROVED
-				
A				

NOTES:

1. ACCEPTANCE SHALL BE IN ACCORDANCE WITH IPC-6011 – 6013. FABRICATE IN ACCORDANCE WITH IPC-6012 CLASS 2.

2. MATERIALS:
   A) LAMINATED PLASTIC SHEET GFN (FR-4) Tg=180 deg C IAW IPC-4101, AND MUST HAVE A UL FLAMMABILITY RATING OF 94V-0 OR BETTER. BOARD MATERIAL MUST BE UL RECOGNIZED, AND VENDOR SHALL AFFIX UL LISTING DESIGNATION ON THE PRINTED CIRCUIT BOARD.

   B) SOLDER PASTE MUST HAVE NO LEAD CONTENT (ROHS COMPLIANT)

   C) COPPER FOIL TO BE IN ACCORDANCE WITH IPC-MF-150. ALL INTERNAL LAYERS TO BE 0.5 OZ. COPPER WEIGHT. FOR EXTERNAL LAYERS, 1.0 OZ. COPPER WEIGHT IS CONSIDERED FINISH.

3. TOLERANCES:
   A) WARP AND TWIST OF BOARD SHALL NOT EXCEED 1% OVER ENTIRE AREA.
   B) DIMENSIONING AND TOLERANCING IAW ANSI Y14.5
   C) CONDUCTIVE WIDTHS AND SPACING SHALL BE WITHIN (.001) OF GERBER DATA.
   D) REMOVE ALL BURRS AND BREAK SHARP EDGES (.015) MAXIMUM.
   E) ALL INSIDE RADII SHALL BE .062 UNLESS OTHERWISE SPECIFIED.
   F) UNLESS OTHERWISE SPECIFIED, ALL HOLE DIAMETERS ARE AFTER PLATING WITH A TOLERANCE OF +/- .002. FINISHED HOLE SIZES GREATER THAN .012 MAY HAVE A TOLERANCE OF +.003 -.010.

4. FINISH:
   A) ALL EXPOSED CONDUCTIVE PATTERN AREAS NOT COVERED WITH SOLDER MASK OR OTHER PLATING SHALL BE PLATED WITH ELECTROLESS NICKEL IMMERSION GOLD (ENIG) 3-6 MICROINCHES OVER NICKEL 100 MICROINCHES MINIMUM. FULL BODY IMMERSION GOLD ACCEPTED.

   B) APPLY SOLDER MASK PER IPC-SM-840, CLASS 2, TYPE B1, TO BOTH SIDES OF THE BOARD OVER BARE COPPER; COLOR BLACK, MATTE FINISH. ALL SOLDER PADS TO BE 100% FREE OF SOLDER MASK.

   C) SILKSCREEN SHALL BE APPLIED TO BOTH SIDES OF THE BOARD WITH GOLD PERMANENT, NON-CONDUCTIVE EPOXY INK. THERE SHALL BE NO SILKSCREEN ON ANY SOLDERABLE COMPONENT PAD.

5. 100% ELECTRICAL VERIFICATION FOR SHORTS AND CONTINUITY REQUIRED USING CUSTOMER SUPPLIED IPC D 356 NETLIST. NOTIFY CUSTOMER OF DISCREPANCIES.

6. UNLESS OTHERWISE SPECIFIED, ALL LAYERS ARE SHOWN AS VIEWED THROUGH THE PWB FROM THE COMPONENT SIDE.

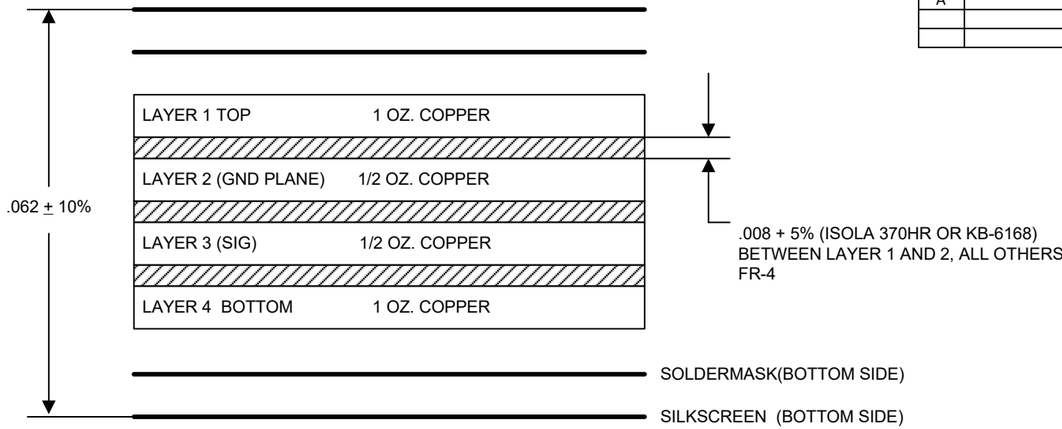
7. ARTWORK IS NOT ISSUED AS PART OF THIS DRAWING AND MUST BE OBTAINED FROM Hip Science, LLC. MASTER ARTWORK FILE(S). THE INFORMATION NECESSARY TO GENERATE THIS ITEM IS SPECIFIED IN THE PATTERN REVISION TABLE.

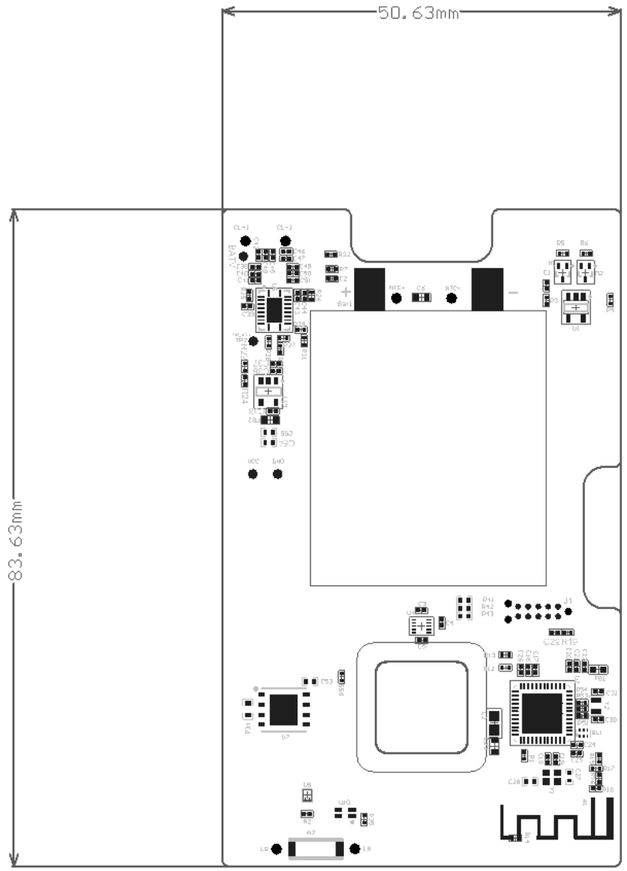
8. MARK DATE CODE AND MANUFACTURERS IDENTIFICATION ON SOLDER SIDE PER IPC-6011; - 6012.

9. FABRICATION AND CONTROLLED IMPEDANCES
   A) THE FOLLOWING ADJUSTMENTS ARE ALLOWED:
      i.) REMOVE NON-FUNCTIONAL INTERNAL PADS
      ii.) ADD TEAR DROPPING
      iii.) REMOVE SOLDER MASK SLIVERS LESS THAN .003 TO ENHANCE PRODUCIBILIITY.

   B) SINGLE-ENDED CONTROLLED IMPEDANCE TRACES ARE AS FOLLOWS:

LAYER	WIDTH	REF LAYER	IMPEDANCE	TOLERANCE
1 (S1)	14	2 (GND)	50 OHMS	+/- 5%





DRAWN BY M. TRISHAUN	DATE	4-MAR-23
CHECKER XXXX	DATE	4-MAR-23
MECHANICAL XXXXX	DATE	4-MAR-23
ELECTRICAL M. TRISHAUN	DATE	4-MAR-23
PROGRAM MGR M. TRISHAUN	DATE	4-MAR-23
PROGRAM	EMNOVATE	

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES AND ARE AFTER PLATING.
TOLERANCE ON ANGLES ±0.5°
TOLERANCE ON DECIMALS 1 PLACE ±0.1, 2 PLACE ±0.01, 3 PLACE ±0.005

MATERIAL: SEE NOTES OR PARTS LIST

THIRD ANGLE PROJECTION

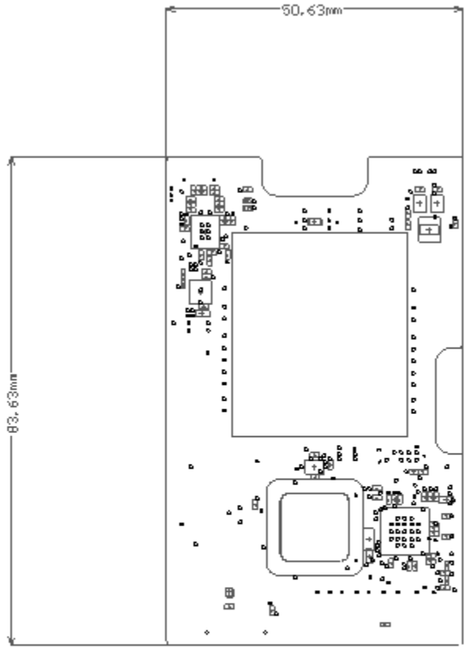
Hip Science, LLC
A Smart Sensor Solution Company
3218 E. Colonial Dr. Ste G
ORLANDO, FL 32803
www.hip-sci.com

DESCRIPTION: Smart Card

SCALE

SIZE	CAGE CODE	DWG NO.
B	750W7	EI7C2652R7REVB

SCALE ---------- UNIT WT. SHEET 1 OF 2



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
☼	3	39.02mil (0.991mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c99h99			
○	6	35.00mil (0.889mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c140h89			
□	226	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v56h25m0mx0			
	235 Total										